



1A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

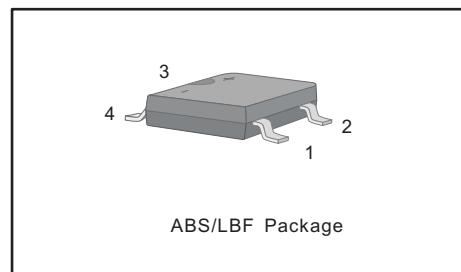
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg / 0.0031oz



Maximum Ratings and Electrical characteristics

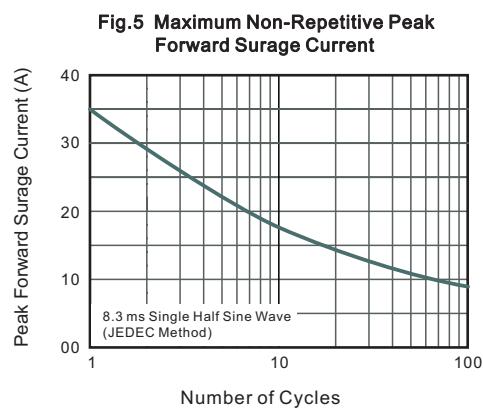
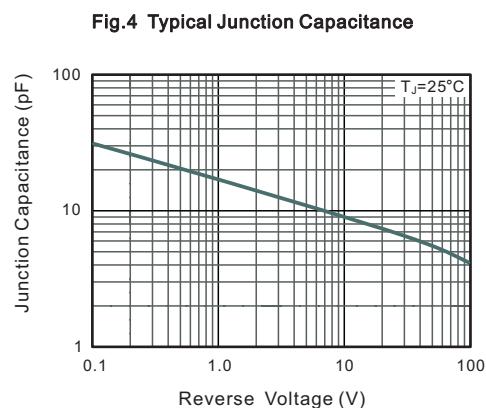
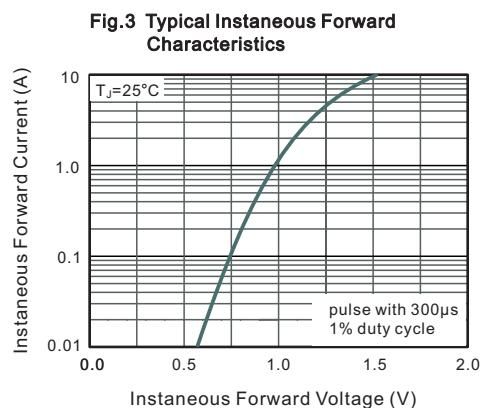
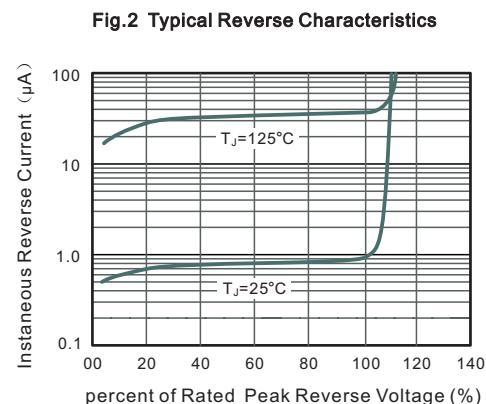
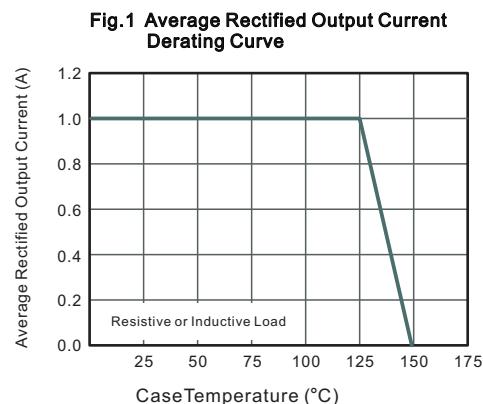
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TB1S-10	TB2S-10	TB4S-10	TB6S-10	TB8S-10	TB10S-10	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T _c = 125 °C	I _o	1						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	35						A
Forward Voltage per element @I _F =1.0A	V _F	1.1						V
Maximum DC Reverse Current @T _A =25 °C @T _A =100°C @T _A =125 °C	I _R	5 50 100						µA
Typical Junction Capacitance (Note1)	C _j	13						pF
Typical Thermal Resistance (Note2)	R _{θJA} R _{θJC}	72 20						°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150						°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

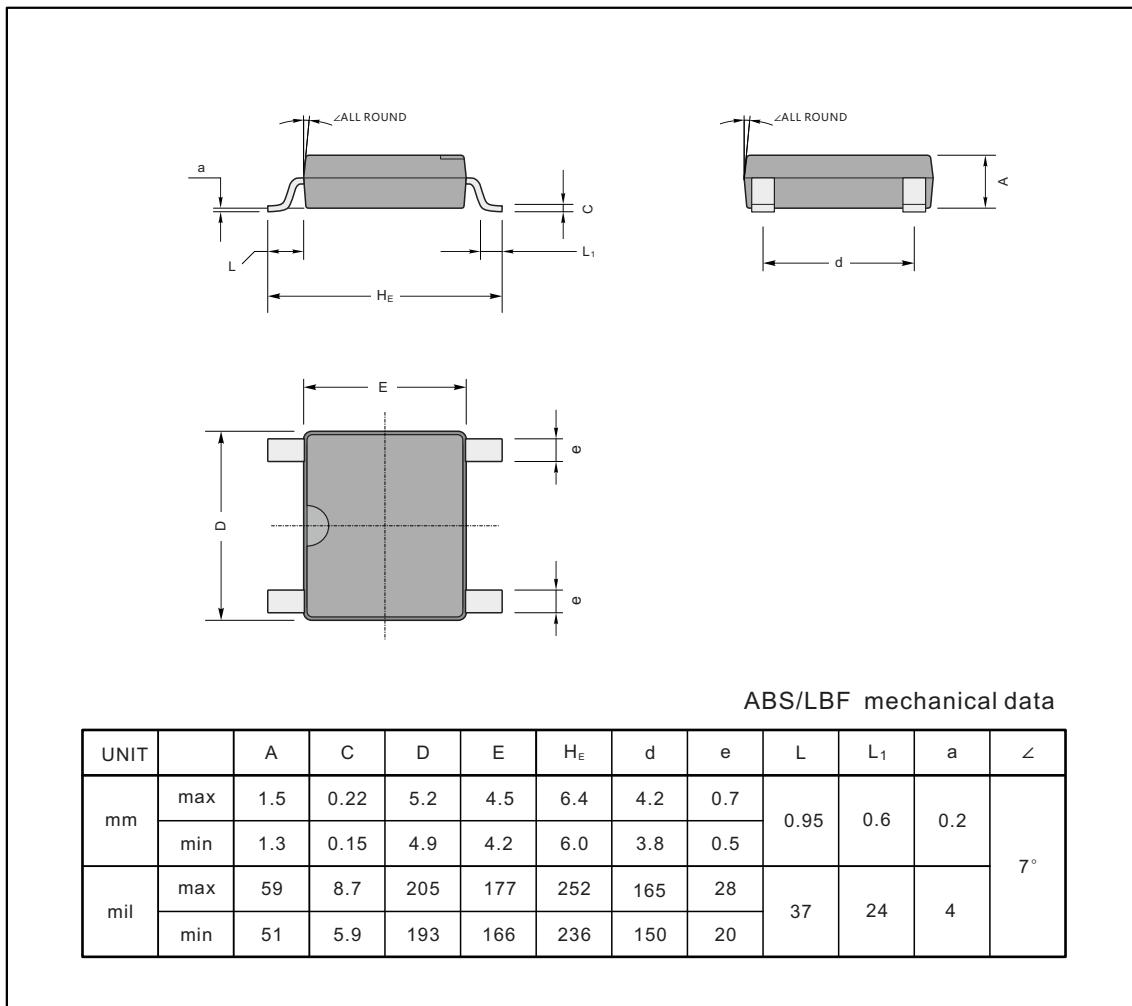




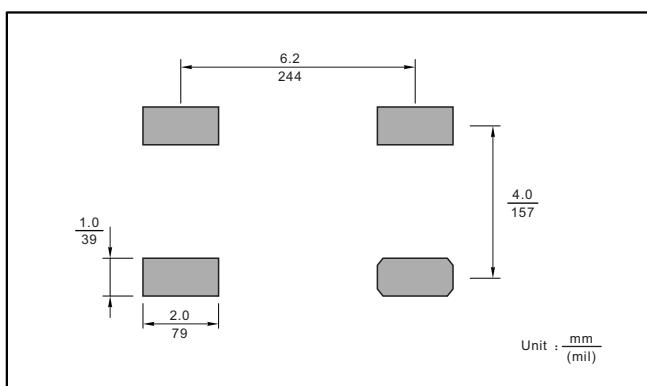
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABS/LBF



The recommended mounting pad size



Marking

Type number	Marking code
TB1S-10	10T1
TB2S-10	10T2
TB4S-10	10T4
TB6S-10	10T6
TB8S-10	10T8
TB10S-10	10T10